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In the Claims:

 (Original) A method of fabricating microstructures comprising: impinging a radiation beam through a substrate that is transparent thereto into a radiation sensitive layer on the substrate to image the microstructures in the radiation sensitive layer.

- 2. (Original) A method according to Claim 1 wherein the radiation sensitive layer is a negative photoresist layer such that portions of the negative photoresist layer that are exposed to the radiation beam remain after development.
- 3. (Original) A method according to Claim 2 wherein the negative photoresist layer is thicker than the microstructures and wherein impinging comprises impinging a radiation beam through a substrate that is transparent thereto into a negative photoresist layer on the substrate to image buried microstructures in the negative photoresist layer, adjacent the substrate.
- 4. (Original) A method according to Claim 2 wherein at least some of the microstructures include a base and a top that is narrower than the base and wherein impinging comprises impinging a radiation beam through a substrate that is transparent thereto into a negative photoresist layer on the substrate to image microstructures in the negative photoresist layer with the bases adjacent the substrate and the tops remote from the substrate.
- 5. (Original) A method according to Claim 2 wherein the negative photoresist layer is of variable thickness thereacross, wherein a minimum thickness of the negative photoresist layer is thicker than the microstructures and wherein impinging comprises impinging a radiation beam through a substrate that is transparent thereto into a negative photoresist layer on the substrate to image buried microstructures beneath the negative photoresist layer, adjacent the substrate, that are independent of the variable thickness of the negative photoresist layer.

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6. (Original) A method according to Claim 2 wherein the negative photoresist layer includes impurities thereon, remote from the substrate, wherein the negative photoresist layer is thicker than the microstructures and wherein impinging comprises impinging a radiation beam through a substrate that is transparent thereto into a negative photoresist layer on the substrate to image buried microstructures in the negative photoresist layer, adjacent the substrate, that are not distorted by the impurities.

- 7. (Original) A method according to Claim 1 wherein the substrate is a flexible substrate.
- 8. (Original) A method according to Claim 1 wherein the radiation sensitive layer is on a cylindrical platform such that the substrate is on the radiation sensitive layer remote from the cylindrical platform, and wherein impinging comprises:

rotating the cylindrical platform about an axis thereof while simultaneously axially rastering the radiation beam through the substrate across at least a portion of the radiation sensitive layer to image the microstructures in the radiation sensitive layer.

- 9. (Original) A method according to Claim 8 further comprising simultaneously translating the cylindrical platform and/or radiation beam axially relative to one another.
- 10. (Original) A method according to Claim 9 further comprising simultaneously continuously varying amplitude of the radiation beam.
- 11. (Original) A method according to Claim 1 wherein the substrate is at least about one square foot in area.
- 12. (Original) A method according to Claim 1 wherein impinging is performed continuously on the substrate for at least about 1 hour.

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13. (Original) A method according to Claim 1 wherein impinging is performed continuously on the substrate for at least about 1 hour to fabricate at least about one million microstructures.

- 14. (Original) A method according to Claim 1 wherein the microstructures comprise optical and/or mechanical microstructures.
- 15. (Original) A method according to Claim 1 further comprising: developing the microstructures that are imaged in the radiation sensitive layer to provide a microstructure master.
- 16. (Original) A method according to Claim 1 wherein the substrate is cylindrical, ellipsoidal or polygonal in shape.
- 17. (Original) A method according to Claim 1 further comprising translating the substrate and/or radiation beam relative to one another while impinging the radiation beam.
- 18. (Original) A method according to Claim 15 further comprising: forming a plurality of second generation stampers directly from the master; and

forming a plurality of third generation microstructure end products directly from a stamper.

19.-20. (Canceled)

21. (Original) A method of fabricating microstructures comprising: impinging a radiation beam into a negative photoresist layer to image the microstructures in the negative photoresist layer, such that portions of the negative photoresist layer that are exposed to the radiation beam remain after development.

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22. (Original) A method according to Claim 21 wherein the negative photoresist layer is thicker than the microstructures and wherein impinging comprises impinging a radiation beam into a negative photoresist layer to image buried microstructures in the negative photoresist layer.

- 23. (Original) A method according to Claim 21 wherein the negative photoresist layer is of variable thickness thereacross, wherein a minimum thickness of the negative photoresist layer is thicker than the microstructures and wherein impinging comprises impinging a radiation beam into the negative photoresist layer to image buried microstructures beneath the negative photoresist layer that are independent of the variable thickness of the negative photoresist layer.
- 24. (Original) A method according to Claim 21 wherein the negative photoresist layer includes impurities thereon, wherein the negative photoresist layer is thicker than the microstructures and wherein impinging comprises impinging a radiation beam into the negative photoresist layer on the substrate to image buried microstructures in the negative photoresist layer that are not distorted by the impurities.
- 25. (Original) A method according to Claim 21 wherein the negative photoresist layer is on a cylindrical platform and wherein impinging comprises:

rotating the cylindrical platform about an axis thereof while simultaneously axially rastering the radiation beam across at least a portion of the negative photoresist layer to image the microstructures in the negative photoresist layer.

- 26. (Original) A method according to Claim 25 further comprising simultaneously translating the cylindrical platform and/or radiation beam axially relative to one another.
- 27. (Original) A method according to Claim 26 further comprising simultaneously continuously varying amplitude of the radiation beam.

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28. (Original) A method according to Claim 21 wherein the negative photoresist layer is at least about one square foot in area.

- 29. (Original) A method according to Claim 21 wherein impinging is performed continuously on the negative photoresist layer for at least about 1 hour.
- 30. (Original) A method according to Claim 21 wherein impinging is performed continuously on the negative photoresist layer for at least about 1 hour to fabricate at least about one million microstructures.
- 31. (Original) A method according to Claim 21 wherein the microstructures comprise optical and/or mechanical microstructures.
- 32. (Original) A method according to Claim 21 wherein the negative photoresist layer is cylindrical, ellipsoidal or polygonal in shape.
- 33. (Original) A method according to Claim 21 further comprising translating the substrate and/or radiation beam relative to one another, while impinging the radiation beam.
- 34. (Original) A method according to Claim 31 further comprising: developing the microstructures that are imaged in the negative photoresist layer to provide a microstructure master.
- 35. (Original) A method according to Claim 34 further comprising: forming a plurality of second generation stampers directly from the master; and

forming a plurality of third generation microstructure end products directly from a stamper.

36.-37. (Canceled)

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38. (Original) A method of fabricating microstructures comprising:

impinging a laser beam through a substrate that is transparent thereto into a negative photoresist layer on the substrate to image the microstructures in the negative photoresist layer, wherein at least some of the microstructures include a base adjacent the substrate and a top that is narrower than the base, remote from the substrate.

- 39. (Original) A method according to Claim 38 wherein the substrate is a flexible substrate.
- 40. (Original) A method according to Claim 38 wherein the negative photoresist layer is on a cylindrical platform such that the substrate is on the negative photoresist layer remote from the cylindrical platform, and wherein impinging comprises:

rotating the cylindrical platform about an axis thereof while simultaneously axially rastering the laser beam through the substrate across at least a portion of the negative photoresist layer to image the microstructures in the negative photoresist layer.

- 41. (Original) A method according to Claim 40 further comprising simultaneously translating the cylindrical platform and/or laser beam axially relative to one another.
- 42. (Original) A method according to Claim 41 further comprising simultaneously continuously varying amplitude of the laser beam.
- 43. (Original) A method according to Claim 38 wherein the microstructures comprise optical and/or mechanical microstructures.
- 44. (Original) A method according to Claim 38 further comprising: developing the microstructures that are imaged in the photoresist layer to provide a microstructure master.

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45. (Original) A method according to Claim 44 further comprising: forming a plurality of second generation stampers directly from the master; and

forming a plurality of third generation microstructure end products directly from a stamper.

46.-107. (Canceled)